



THE WHEDA FOUNDATION, INC.
2023 HOUSING GRANT PROGRAM COMPETITION

BINDING AGREEMENT IF APPLICANT IS AWARDED AND ACCEPTS GRANT

Applicant agrees to the following terms and conditions if it accepts an award under this Application (the "Grant") : it shall use the Grant solely for purposes stated in the Application; if the Application includes housing, warrant it is an "eligible sponsor" of "housing projects" under Wis. Stat., Chapter 234; retain, for audit purposes, all financial and program materials for five years; allow the WHEDA Foundation, the Authority, and their representatives, to examine, audit, and obtain copies of its books, documents, and records relating to the Grant; comply with all applicable federal, state and local laws; amend this agreement only in writing; report completion of the Grant by providing a written narrative that identifies Grant project start and completion dates, summarizes project activities and total funds expended; proof of completion through paid invoices and/or pictures; return unused or rescinded WHEDA Foundation Grant funds; be governed under the laws of the state of Wisconsin; the Grant and this agreement shall not be construed as constituting a partnership, joint venture, or employer/employee relationship; that third persons have no rights under the Grant or this agreement; that no waiver of any breach shall be a waiver of any other or subsequent breach. Acceptance of any Grant funds by Applicant shall be conclusive evidence of its agreement to these terms and conditions.

APPLICATION SUBMITTAL AUTHORIZATION AND CERTIFICATION

On behalf of _____, we submit this Application for the 2023 WHEDA Foundation Housing Grant Program competition. We hereby certify all the information contained herein is accurate and complete. We acknowledge that the above terms and conditions shall be a binding contract if we accept an award.

(To be dated and signed by the chief officer of the board and chief professional staff member)

Date: _____, 2023

Date: _____, 2023

Signature

Signature

Print Name

Print Name

Title

Title

APPLICATION SUBMISSION REMINDER

Completed application packages must be electronically submitted no later than **August 11, 2023, at 11:59 PM.**